

Specifications

Concept	DC-motor driven Z-linear-axis, Single-board-PC, menu-controlled Teach-In, Operating and menu access via shuttle-wheel with push-button
Wire-types	Au-wire: 17,5...50 µm on 2" spool (opt. ½ ") Ribbon size: 30 / 12,5 – 250 / 25 µm Wedge / Wedge Alu / Au-wire 17,5 – 75 µm
Bondhead	Contactless electronic Touchdown-Sensor US-Generator 0...5 W programmable, 60 kHz standard, other frequencies optional Negative Flame-Off Bondforce 15 until 150 cN electrically adjustable Capillaries: 9 – 16mm length Step precision : 1 µm
Display	6,5" TFT Color-Display, 640x480 Pixel (VGA)
Working area	Bondhead linear Z travel: 60 mm; Standard workheight: 55mm Manipulator in X and Y: 18 x 18 mm Respond reduction: 1:7
Substrate-holder	Digitally controlled heated stage, up to 360°C Standard Ø 60 mm for tools up to 2" x 2", mechanical clamping 4" x 4", 80 mm and 95 mm Ø optional, also with vacuum
Control-modes:	Manual, semi-automatic Programline-Step for testing via Shuttle-wheel
Loop-types:	Ball-Wedge / Wedge-Wedge, Bumping, Reverse, Stitch Loopheights programmable
Dimensions	Height: 400mm, width: 630mm, depth: 580mm, weight approx. 30kg
Programme Memory	internal hard disk 40 GB
Connections:	100...230 VAC, single-phase; pot. Air-pressure / vacuum Ø 6 mm USB – plug for printer

Version
E/2006



53XX

BDA
Ball + Deep Access
Wedge Bonder

The bondhead is an universal version. The customer can use it as well as Ballbonder and DA Wedge-Wedge- or DA Ribbon Bonder, due to the easy change of the bondtools. The motor driven Z-topclamp enables the wire cut and also the reproducible tailbuilding during the bondprocess. The 60 mm Z-axis enables the user to bond complexe and high construction samples without any mechanical change.

Deep Access area: ballbonding 12mm, Wedge/Wedge until 20 mm (1" Tool).

Additionally every parameter can be saved to the internal harddisk. You always work with repeatable results – also after a lot of years. The handling, supported by a colour display and the input with an shuttle-wheel make the programming of the machine very easy. The operator can create different kinds of loops with the manipulator system. Operators require only a minimum of training, making the 53xx manual ball bonder the ideal choice for prototype, rework and small-scale production.

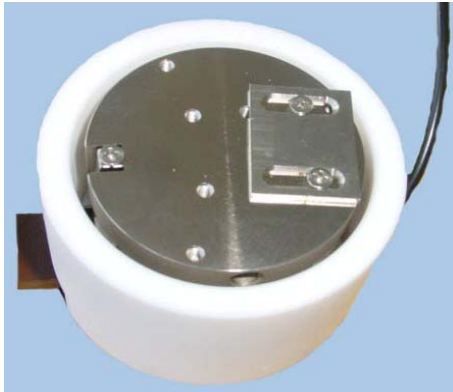
The 53xx is perfect suited for complex bond- tasks, optimal quality and the most favourable price. This machine is the right choice for such applications.

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Option
TB0000.92.000
heated
Ø 60mm, mechanical clamping

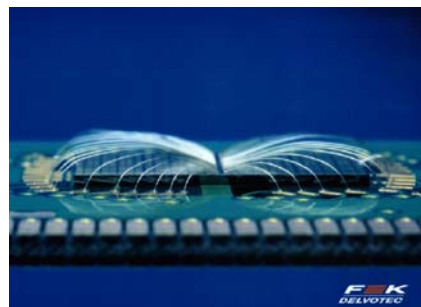
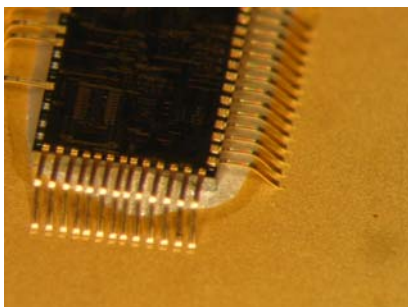
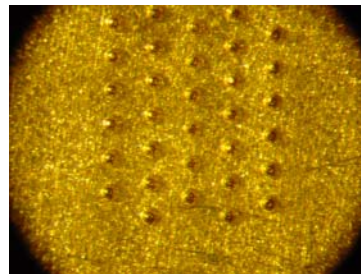
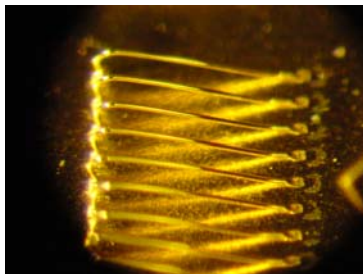


Option
TB0000.87.000
heated
Ø 80mm, mechanical clamping and
vacuum



Option
4-0402-210-0
heated
4x4", mechanical clamping and vacuum

Version
E/2006



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